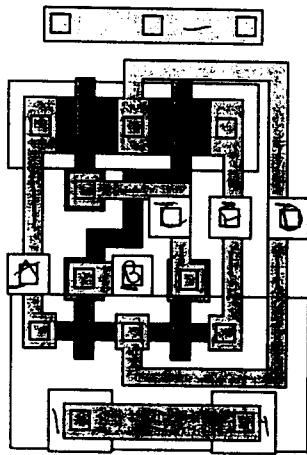


Consider the following plot of a CMOS3DLM circuit.

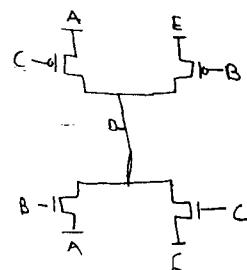
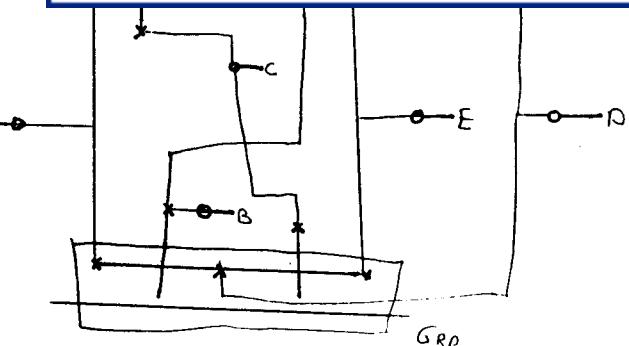


a) Determine the function of the circuit. Do this by drawing a STICKS diagram of the circuit and determining a truth table for the circuit. Use the following page. When drawing the STICKS diagram use standard E.E. 451.3 colors:

CMOS3DLM Layer	Color
N+ diffusion	Green
P+ diffusion	Orange
Polysilicon	Red
P-Well	Brown
Metal 1	Blue
Metal 2	Black
Contact Cut	X
Via	O

b) Indicate the number of each of the following:

- N channel transistors 2
- P channel transistors 2
- Input ports 3
- Output ports 2
- N-Well substrate contacts 6



10

B	C	D	A	E
0	0	0	0	0
0	0	1	1	1
0	1	0	X	0
1	0	0	0	X
1	0	1	1	X
1	1	0	0	0
1	1	1	1	1
0	1	X	1	1

"Well, I've wrestled with reality
for 35 years, Doctor, and I'm happy
to state I finally won out over it."

(1)

$$t_{dF} = \frac{t_F}{2} \quad t_{dR} = t_F/2$$

$$t_F = A_N Q \quad t_R = A_P Q$$

using table 4.9 \rightarrow Nand3 Spice & only #'s I could find

$$t_{dF} = 0.255 \text{ ns}$$

$$t_{dR} = 0.42 \text{ ns}$$

t_{tr}

$$t_{dF} = 0.225 \text{ ns}$$

$$t_F = 0.45 \text{ ns}$$

$$\text{Pulse length} = 2(0.42 \text{ ns}) + 2(0.255 \text{ ns}) + 2(0.42 \text{ ns}) + 0.45 \text{ ns}$$

$$= 2.61 \text{ ns}$$

10

$$t_f = 2(0.42) = 0.84 \text{ ns}$$

$$(6) 3g = 3(6.9 \times 10^{-19} \text{ C})(L \times W)$$

\rightarrow would ensure better charge sharing
 \rightarrow decrease rise and fall times
 \rightarrow if big enough would eliminate spark

"In college I usually stayed up very late working with my roommates, Rob Stavis, Bob Stem, and Ken Stover, on important academic projects such as ordering pizza or assembling the legendary Two-Man Submarine. This was a miniature submarine that we obtained by sending \$9.95 away to a company that advertised in Marvel comics. It came in a small, lightweight, very flat box, but when we assembled all the parts, we had an actual working two-man submarine in every possible respect except that (1) the two men could not be in it simultaneously, and (2) being constructed entirely out of cardboard, it was not ideally suited for the underwater environment."

SPECIFIC INSTRUCTIONS FOR THE EXAMINATION

- 1) All designs use standard CMOS3DLM design rules and layers. $V_{DD} = +5V$ and $V_{SS} = 0V$.
- 2) Unless otherwise specified, normal substrate connections are assumed for all P-channel and N-channel transistors, i.e., V_{SS} for N-channel and V_{DD} for P-channel.
- 3) CMOS3DLM resistance and capacitance parameters are as follows:

Layer	Resistance	Capacitance
N-Diffusion	25.0 Ω/\square	4.4E-4 $\text{pF}/\mu\text{m}^2$
P-Diffusion	80.0 Ω/\square	1.5E-4 $\text{pF}/\mu\text{m}^2$
Polysilicon	18.0 Ω/\square	6.0E-5 $\text{pF}/\mu\text{m}^2$
Metal 1	0.035 Ω/\square	2.7E-5 $\text{pF}/\mu\text{m}^2$
Metal 2	0.030 Ω/\square	1.4E-5 $\text{pF}/\mu\text{m}^2$
N-Transistor	4275 Ω/\square	See below
P-Transistor	13600 Ω/\square	See below
Gate-channel	See above	6.9E-4 $\text{pF}/\mu\text{m}^2$

- 4) Supplementary physical constants are as follows:

Constant	Symbol	Value	Units
Electron charge	q	1.602E-19	coulomb
Boltzmann's constant	k	1.38E-23	Joule/K
Intrinsic carrier concentration of Si @ T=300K (27°C)	n_i^2	2.1E+20	(carriers/cm ³) ²
Permittivity of free space	ϵ_0	8.854E-14	Farad/cm
Permittivity of Si	ϵ_s	11.7 ϵ_0	Farad/cm
Permittivity of SiO ₂	ϵ_{ox}	3.9 ϵ_0	Farad/cm

- 5) (H)SPICE process parameters are as follows:

Parameter	Name	N-channel	P-channel	Units
V_t	Zero-bias threshold voltage	0.7	0.8	Volts
κ'	Process gain factor	40.0E-6	12.0E-6	A/V^2
γ	Bulk threshold body factor	1.1	0.6	$\text{V}^{1/2}$
$2 k_{\text{B}} T$	Surface potential	0.6	0.6	V
λ	Channel length modulation factor	1.0E-2	3.0E-2	1/V
t_{ox}	Oxide thickness	5.0E-6	5.0E-6	cm
N_A or N_D	Substrate doping density	1.7E+16	5.0E+15	$1/\text{cm}^3$
μ	Carrier surface mobility	775	250	$\text{cm}^2/(\text{V}\cdot\text{sec})$

tab 5047e

ne: _____

Student Number: _____